



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25°C
Q1	25V	4Ω @ V _{GS} = 4.5V	0.4 A
02	201/	80mΩ @ V _{GS} = -12V	-3.2 A
Q2	-30V	125mΩ @ V _{GS} = -4.5V	-2.6 A

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

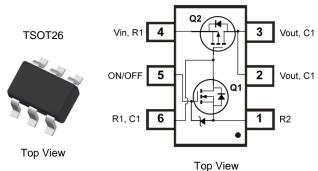
- DC-DC Converters
- Power Management Functions
- Load Switch

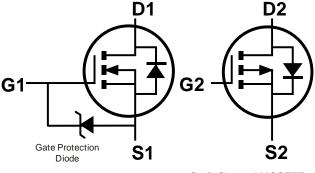
Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Gate on N-Channel (>6kV Human Body Model)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.013 grams (Approximate)





Q1 N-Channel MOSFET

Q2 P-Channel MOSFET

Ordering Information (Note 4)

Part Number	Case	Packaging
DMC25D0UVT-7	TSOT26	3000 / Tape & Reel
DMC25D0UVT-13	TSOT26	10000 / Tape & Reel

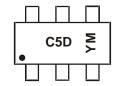
Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

Internal Circuit

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



 $\begin{array}{l} C5D = \underline{P}roduct \ Type \ Marking \ Code \\ YM \ \underline{or} \ YM = Date \ Code \ Marking \\ Y \ \underline{or} \ \overline{Y} = Year \ (ex: \ C = 2015) \\ M = Month \ (ex: \ 9 = September) \end{array}$

Date Code Key

Year	201	5	2016		2017	20	18	2019		2020	2	2021
Code	С		D		Е		=	G		Н		
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings – Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	25	V
Gate-Source Voltage	V _{GSS}	-0.5 +8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	I _D	0.4	Α
Maximum Continuous Body Diode Forward Current (Note 6)	Is	1.2	Α
Pulsed Drain Current (Note 6)	I _{DM}	1.5	Α

Maximum Ratings – Q2 (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	-30	V	
Gate-Source Voltage	V _{GSS}	±12	V	
Continuous Drain Current (Note 5) V 10V	Steady State		-3.2	Α
Continuous Drain Current (Note 5) V _{GS} = -10V	ID	-14.4	Α	
Continuous Drain Current (Note 5) V _{GS} = -4.5V			-2.6	Α
Maximum Continuous Body Diode Forward Current (Note 6)	IS	-1.2	Α	
Pulsed Drain Current (Note 6)		I _{DM}	-20	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Power Dissipation (Note 5)		P_{D}	1.2	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	101	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	5	C/VV		
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	37	°C/W		
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

Electrical Characteristics - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)				l .		
Drain-Source Breakdown Voltage	BV _{DSS}	25	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.65	0.85	1.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	3.8	4	Ω	$V_{GS} = 4.5V, I_D = 0.4A$
Diode Forward Voltage	V_{SD}	_	0.76	1.2	V	$V_{GS} = 0V, I_{S} = 0.29A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	l	26.2	_		$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz
Output Capacitance	Coss		7.1	_	pF	
Reverse Transfer Capacitance	C _{rss}	_	2.7	_		I = 1.0WII IZ
Gate Resistance	Rg	_	84.5	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	0.4	_		
Total Gate Charge (V _{GS} = 8V)	Qg	_	0.7	_	nC	V 5V 1 0 0A
Gate-Source Charge	Qgs	_	0.1	_	IIC	$V_{DS} = 5V, I_{D} = 0.2A$
Gate-Drain Charge	Q_{gd}	_	0.1	_		
Turn-On Delay Time	t _{D(ON)}	_	3	_		
Turn-On Rise Time	t _R	_	2.3	_		$V_{GS} = 4.5V, V_{DS} = 6V,$
Turn-Off Delay Time	t _{D(OFF)}	_	7.7	_	ns	$R_G = 50\Omega, I_D = 0.5A$
Turn-Off Fall Time	t _F	_	3.7	_		

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 6. Repetitive rating, pulse width limited by junction temperature. 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.

 9. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%.



Electrical Characteristics – Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 10)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}		_	-1	μΑ	$V_{DS} = -24V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 10)						
Gate Threshold Voltage	V _{GS(TH)}	-0.5	-0.9	-1.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
		_	59	80		$V_{GS} = -12V, I_D = -2.3A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	75	125	mΩ	$V_{GS} = -4.5V, I_{D} = -1.9A$
		_	_	300		V _{GS} = -2.5V, I _D = -1A
Diode Forward Voltage	V_{SD}	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 11)				•		
Input Capacitance	C _{iss}	_	854	_		
Output Capacitance	C _{oss}	_	53	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1MHz
Reverse Transfer Capacitance	C _{rss}	_	47	_		I = IIVIMZ
Gate Resistance	Rq	_	11	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qq	_	10	_		
Total Gate Charge (V _{GS} = -10V)	Qq	_	21	_		15)/ 1 40
Gate-Source Charge	Q _{gs}	_	1.5	_	nC	$V_{DS} = -15V, I_{D} = -4A$
Gate-Drain Charge	Q _{qd}	_	2.8	_	1	
Turn-On Delay Time	t _{D(ON)}	_	3.5	_		
Turn-On Rise Time	t _R	_	3.3	_	1	$V_{GS} = -10V, V_{DS} = -15V,$
Turn-Off Delay Time	t _{D(OFF)}	_	61.4	_	ns	$R_G = 6\Omega$, $I_D = -1A$
Turn-Off Fall Time	t _F	_	14.6	_		

Notes:

- 10. Short duration pulse test used to minimize self-heating effect.
- 11. Guaranteed by design. Not subject to production testing.

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Typical Characteristics - N-CHANNEL

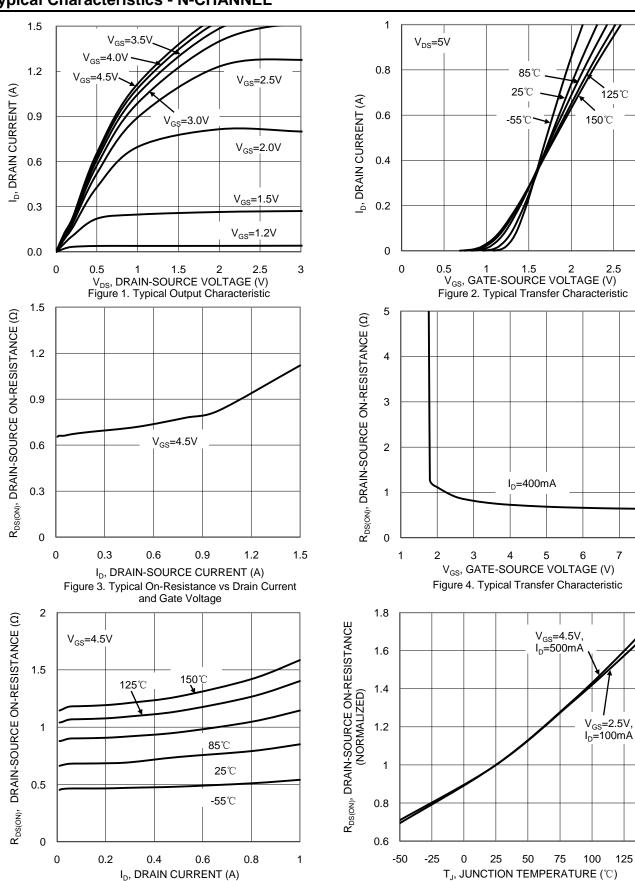


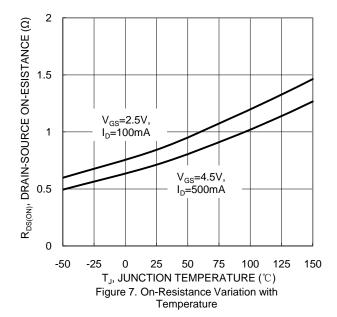
Figure 5. Typical On-Resistance vs Drain Current and

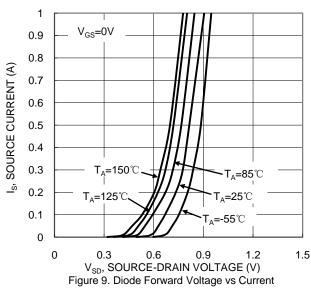
Temperature

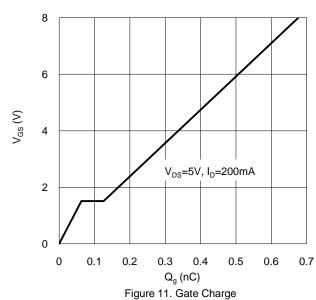
Figure 6. On-Resistance Variation with Temperature

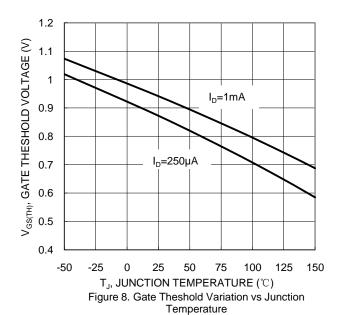
150

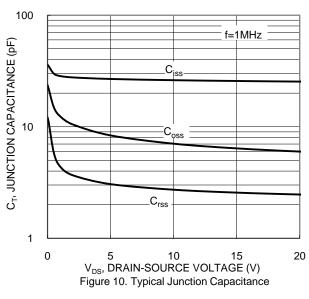


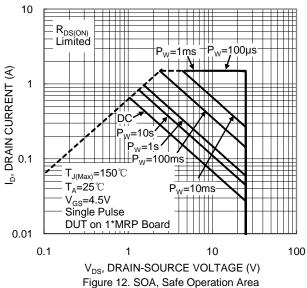




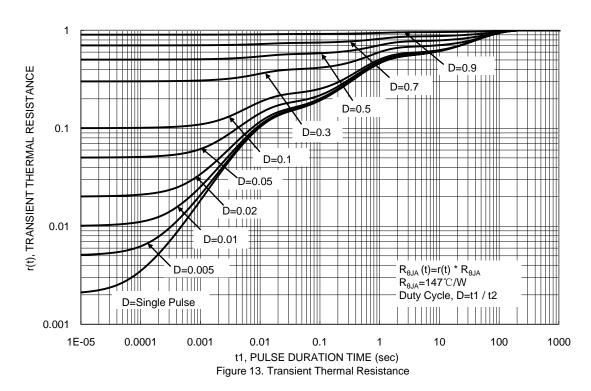






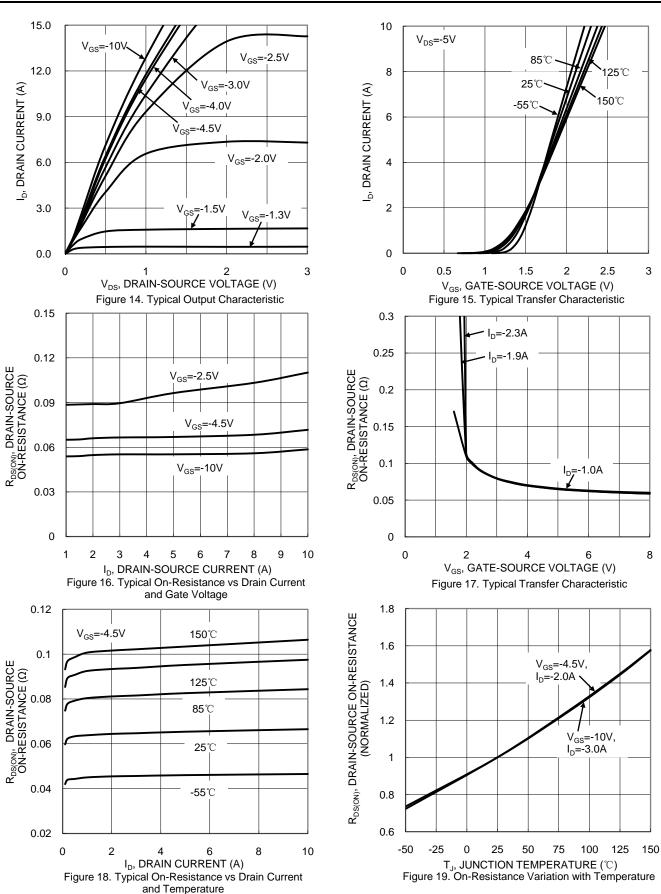








Typical Characteristics - P-CHANNEL





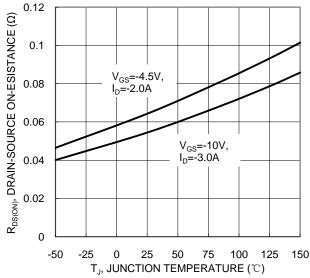
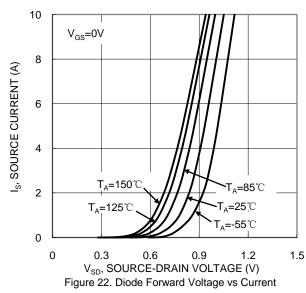
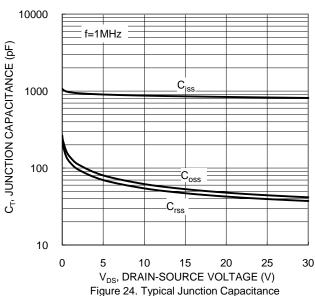
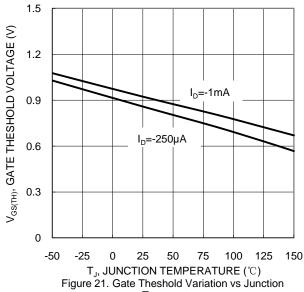


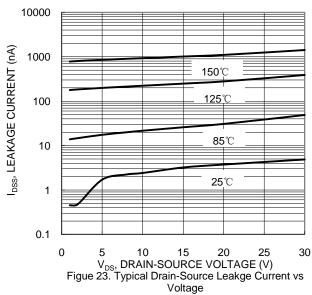
Figure 20. On-Resistance Variation with Temperature







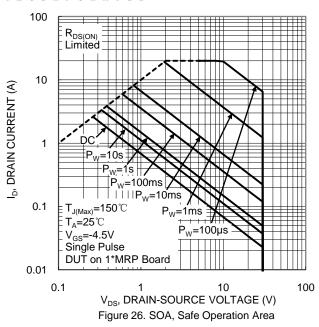
Temperature



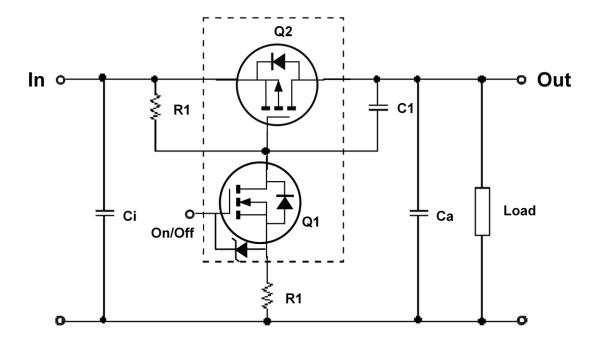
10 8 6 $V_{GS}(V)$ 4 V_{DS} =-15V, I_{D} =-4A 2 0 2 10 12 14 16 18 20 22 0 4 Q_g (nC)

Figure 25. Gate Charge





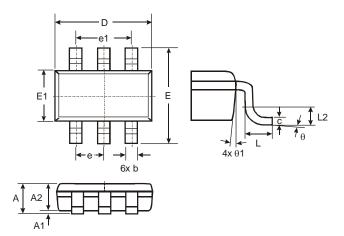
Application Circuit





Package Outline Dimensions

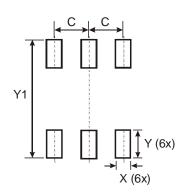
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TSOT26						
Dim	Min	Max	Тур			
Α	_	1.00	-			
A1	0.01	0.10	_			
A2	0.84	0.90	_			
D	-	_	2.90			
Е	_	_	2.80			
E1	_	_	1.60			
b	0.30	0.45	_			
С	0.12	0.20	_			
е	_	_	0.95			
e1	_	_	1.90			
L	0.30	0.50				
L2	_	_	0.25			
θ	0°	8°	4°			
θ1	4°	12°	_			
All D	imensi	ons in	mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
X	0.700
Y	1.000
Y1	3.199



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